

Chapter 2

Ideal Transmission Line Fundamentals

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Outline

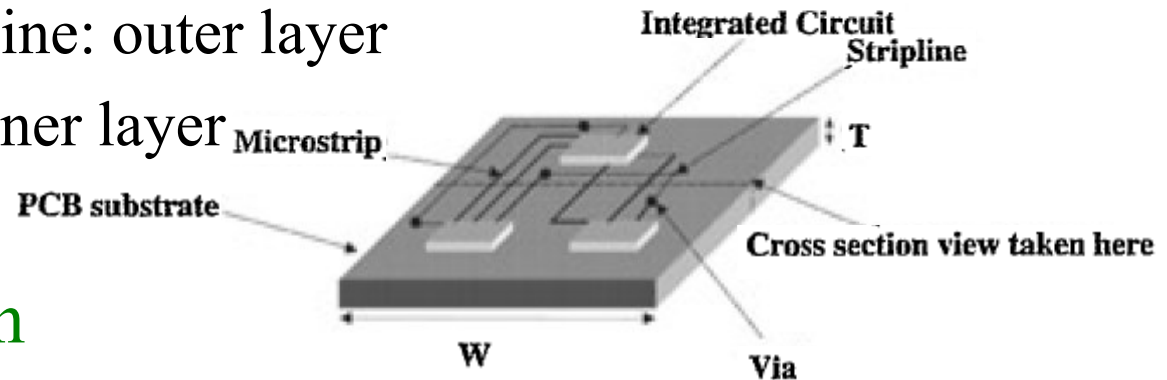
- Transmission Line Structures on a PCB or MCM
- Wave Propagation
- Transmission Line Parameters
- Launching Initial Wave and Transmission Line Reflections
- Additional Examples

Transmission Line Structures on a PCB or MCM

- Typical Design Built on a PCB

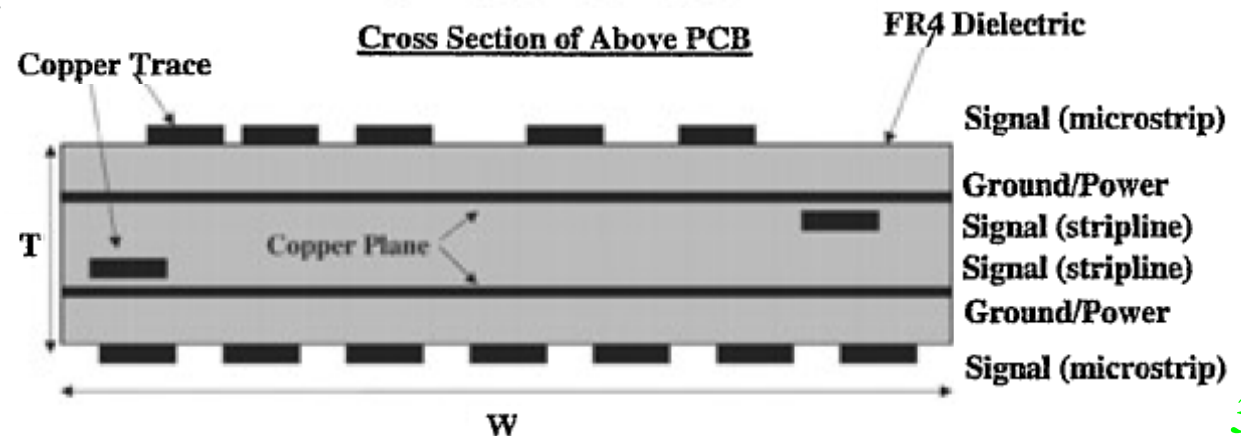
- 3D View

- Microstrip line: outer layer
 - Stripline: inner layer



- Cross Section

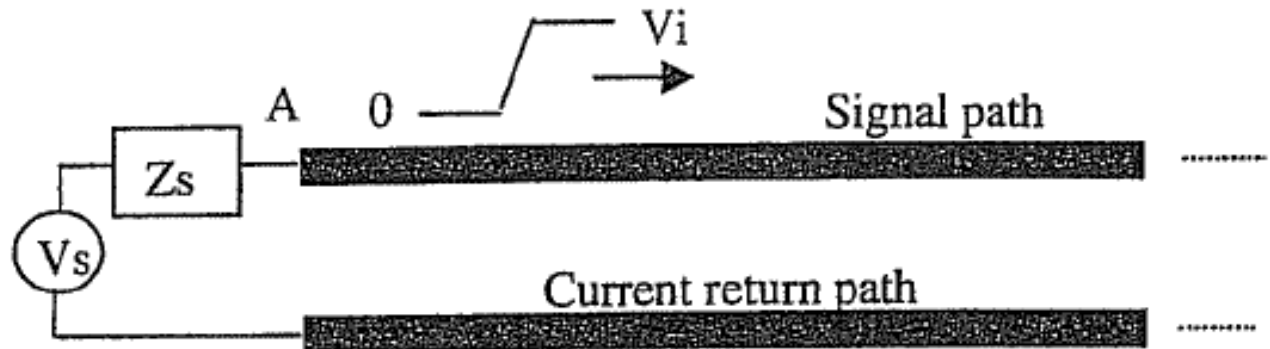
- For *ac* signal: Ground/Power could be viewed as *ac* ground.



Typical conductor:
copper
Typical dielectric:
FR4

Wave Propagation

- Transmission Line Propagation
 - Typical Method of Portraying a Digital Signal
 - When the **rise time or fall time** is small compared to the **propagation delay** down the trace.
 - Wave propagation is like the waterfront.
 - Voltage: height of the water
 - Current: flow of the water
 - V_s and Z_s : source or driver (output buffer)



Transmission Line Parameters

- Introduction

- Characteristic Impedance

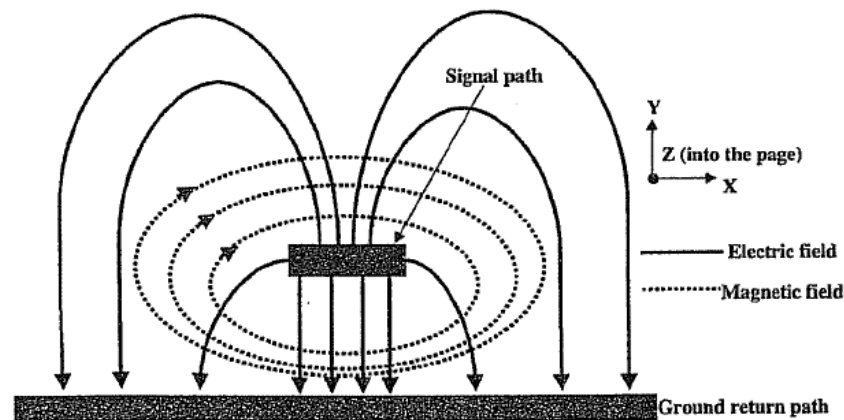
- V/I for a matched load (the impedance for the wave)

- Propagation Velocity

- The speed of the wave

- Relationship between (V, I) and (E, H)

- Actually, transmission lines transfer energy using (E, H) .

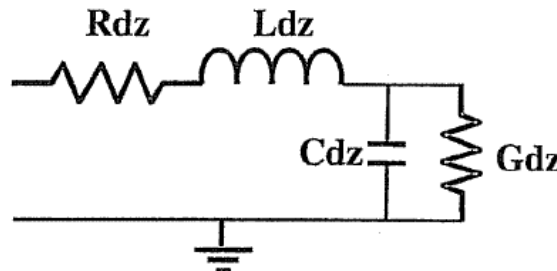


Transmission Line Parameters

- Introduction

- Equivalent Circuit

- TEM: When **no components** of the E or H fields propagate **in the z -direction**.
 - R : the losses due to the **finite conductivity of the conductor**
 - L : the energy stored in the **magnetic field**
 - C : the energy stored in the **electric field**
 - G : the losses due to the **finite resistance of the dielectric** separating the conductor and the ground plane

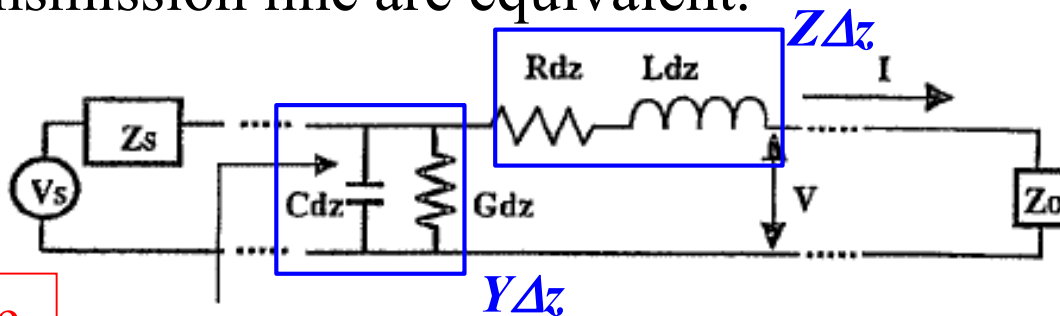


Transmission Line Parameters

- Derivation and Detailed Descriptions

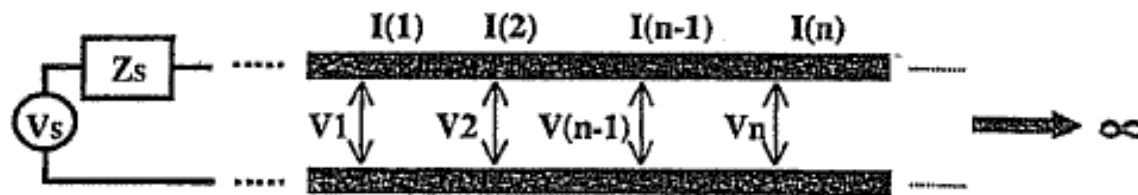
- Characteristic Impedance

- The following two circuit representations of a transmission line are equivalent.



How small the value of dz is reasonable?

(a)



(b)

Equivalent representation (Z_0 and γ)



Lossless (Z_0 and β)

Transmission Line Parameters

- Derivation and Detailed Descriptions

- Characteristic Impedance

- With a short length of Δz , the derivation is as follows:

$$j\omega L(\Delta z) + R(\Delta z) = Z\Delta z \quad (\text{series impedance for length of line } \Delta z)$$

$$j\omega C(\Delta z) + G(\Delta z) = Y\Delta z \quad (\text{parallel admittance for length of line } \Delta z)$$

$Y\Delta z$ in parallel with $Z\Delta z + Z_0$.

$$Z(\text{input}) = Z_o = \frac{(Z_o + Z\Delta z)(1/Y\Delta z)}{Z_o + Z\Delta z + 1/Y\Delta z} \quad (\text{assuming the load is equal to the characteristic impedance})$$

$$\longrightarrow Z_o \left(Z\Delta z + Z_o + \frac{1}{Y\Delta z} \right) = (Z_o + Z\Delta z) \frac{1}{Y\Delta z}$$

$$\Rightarrow Z_o Z\Delta z + Z_o^2 + \cancel{\frac{Z_o}{Y\Delta z}} = \cancel{\frac{Z_o}{Y\Delta z}} + \frac{Z\Delta z}{Y\Delta z}$$

$$\Rightarrow Z_o(Z\Delta z + Z_o) = \frac{Z}{Y}$$

$$\Rightarrow Z_o Y(Z\Delta z + Z_o) = Z$$

$$\Rightarrow \lim_{\Delta z \rightarrow 0} [Z] = Z_o^2 Y$$

Transmission Line Parameters

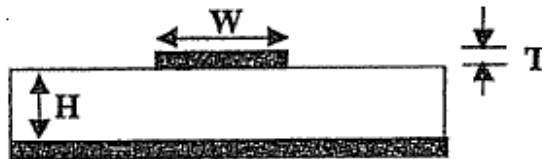
- Derivation and Detailed Descriptions
 - Characteristic Impedance

$$\longrightarrow Z_o = \sqrt{\frac{Z}{Y}} = \sqrt{\frac{R + j\omega L}{G + j\omega C}}$$

- When the line is **lossless**, we have $Z_o = \sqrt{L/C}$
- Only at **very high frequencies**, or with **very lossy lines**, do the R and G components of the impedance become significant.

– Approximations for Typical TX lines

- Microstrip line

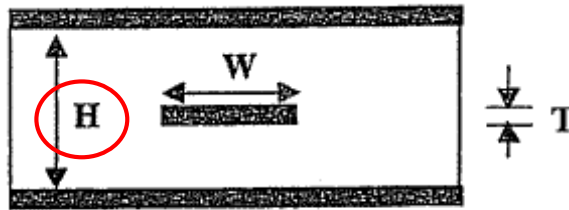


$$Z_o \approx \frac{87}{\sqrt{\epsilon_r + 1.41}} \ln \left(\frac{5.98H}{0.8W + T} \right) \quad \text{Ohms}$$

(Valid when $0.1 < W/H < 2.0$ and $1 < \epsilon_r < 15$)

Transmission Line Parameters

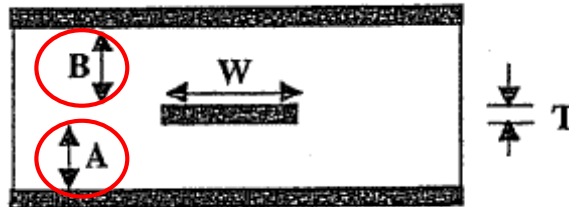
- Derivation and Detailed Descriptions
 - Approximations for Typical TX lines
 - Stripline



$$Z_{0_{sym}} \approx \frac{60}{\sqrt{\epsilon_r}} \ln \left(\frac{4H}{0.67\pi(T + 0.8W)} \right) \text{ Ohms}$$

(Valid when $W/H < 0.35$ and $T/H < 0.25$)

(b)



$$Z_{0_{offset}} \approx 2 \frac{Z_{0_{sym}}(2A, W, T, \epsilon_r) \cdot Z_{0_{sym}}(2B, W, T, \epsilon_r)}{Z_{0_{sym}}(2A, W, T, \epsilon_r) + Z_{0_{sym}}(2B, W, T, \epsilon_r)}$$

(c)

Average by using the equation in (b)

Transmission Line Parameters

- Derivation and Detailed Descriptions
 - Propagation Velocity, Time, and Distance

$$v = \frac{c}{\sqrt{\epsilon_r}}$$

v = propagation velocity, in meters/second

c = speed of light in a vacuum (3×10^8 m/s)

$$PD = \frac{1}{v} = \frac{\sqrt{\epsilon_r}}{c}$$

$$TD = \frac{x\sqrt{\epsilon_r}}{c}$$

ϵ_r = dielectric constant

PD = propagation delay, in seconds per meter

TD = time delay for a signal to propagate down a transmission line of length x

x = length of the transmission line, in meters

- The time delay could also be expressed as $TD = \sqrt{LC}$

- where L : total series inductance of length x

- and C : total shunt capacitance of length x

$$PD = \sqrt{L_{unit} C_{unit}}$$

Transmission Line Parameters

- Derivation and Detailed Descriptions
 - Propagation Velocity, Time, and Distance
 - **TD** depends on the **dielectric constant** of the dielectric material, **the line length**, and the geometry of the transmission line **cross section**.
 - For the same FR4 board:
 - **Stripline**: the effective dielectric constant **is larger** → the speed of the signal is slower → **TD is larger**
 - **Microstrip line**: the effective dielectric constant **is smaller** → the speed of the signal is faster → **TD is smaller**
 - **Formula for** calculating the effective dielectric constant of a **microstrip line**:
$$\epsilon_e = \frac{\epsilon_r + 1}{2} + \frac{\epsilon_r - 1}{2} \left(1 + \frac{12H}{W} \right)^{-1/2} + F - 0.217(\epsilon_r - 1) \frac{T}{\sqrt{WH}}$$
$$F = \begin{cases} 0.02(\epsilon_r - 1) \left(1 - \frac{W}{H} \right)^2 & \text{for } \frac{W}{H} < 1 \\ 0 & \text{for } \frac{W}{H} > 1 \end{cases}$$

Transmission Line Parameters

- Derivation and Detailed Descriptions
 - Equivalent Circuit Models for SPICE Simulation
 - Since it is not practical to model a transmission line with an infinite number of elements, a sufficient number can be determined based on the minimum rise or fall time.
 - TD is no larger than one-tenth of the minimum system rise or fall time.
 - Rise times are typically measured between the 10 and 90% values of the maximum swing.

Transmission Line Parameters

- Derivation and Detailed Descriptions
 - Equivalent Circuit Models for SPICE Simulation

- How many segments should be chosen? $\text{segments} \geq 10 \left(\frac{x}{T_r v} \right)$
- The circuit parameters for a single segment must be

$$C_{\text{segment}} = \frac{(x)(C/\text{meter})}{\text{segments}}$$

$$L_{\text{segment}} = \frac{(x)L/\text{meter}}{\text{segments}}$$

$$R_{\text{segment}} = \frac{(x)R/\text{meter}}{\text{segments}}$$

$$G_{\text{segment}} = \frac{(x)G/\text{meter}}{\text{segments}}$$

$$\text{TD}_{\text{segment}} = \sqrt{L_{\text{segment}} C_{\text{segment}}} \leq \frac{T_r}{10}$$

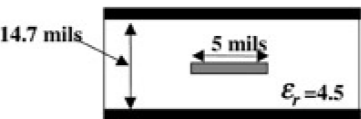
$$(x/v)/(T_r/10)$$

Transmission Line Parameters

- Derivation and Detailed Descriptions

- Example 2.1 Creating a TX Line Model

- $Z_0=50\Omega$, line length $x=5$ in., $\tau_r=2.5$ ns, $\epsilon_r=4.5$.
- First, **using the equations** mentioned previously



$$Z_o \approx \frac{60}{\sqrt{\epsilon_r}} \ln \frac{4H}{0.67\pi(T + 0.8W)} = \frac{60}{\sqrt{\epsilon_r}} \ln \frac{4(14.7)}{0.67\pi[0.7 + 0.8(5)]} = 50 \Omega$$

$$TD = \frac{x\sqrt{\epsilon_r}}{c} = 5 \text{ in.} (0.0254 \text{ m/in.}) \frac{\sqrt{4.5}}{3 \times 10^8 \text{ m/s}} = 898 \text{ ps}$$

$$v = \frac{c}{\sqrt{\epsilon_r}} = \frac{3 \times 10^8 \text{ m/s}}{\sqrt{4.5}} = 1.41 \times 10^8 \text{ m/s}$$

- **The total inductance and capacitance** are

$$\left. \begin{array}{l} TD = \sqrt{LC} \\ Z_o = \sqrt{L/C} \end{array} \right\} \begin{array}{l} L_{\text{total}} = (TD)(Z_o) = (898 \times 10^{-12})(50 \Omega) = 44.9 \text{ nH} \\ C_{\text{total}} = \frac{TD}{Z_o} = \frac{898 \times 10^{-12} \text{ s}}{50 \Omega} = 17.9 \text{ pF} \end{array}$$

Transmission Line Parameters

- Derivation and Detailed Descriptions

- Example 2.1 Creating a TX Line Model

- The segments needed are

$$\text{segments} \geq 10 \left(\frac{X}{T_r v} \right) = 10 \left[\frac{5 \text{ in.}(0.0254 \text{ m/in.})}{2.5 \text{ ns}(1.41 \times 10^8 \text{ m/s})} \right] = 3.6$$

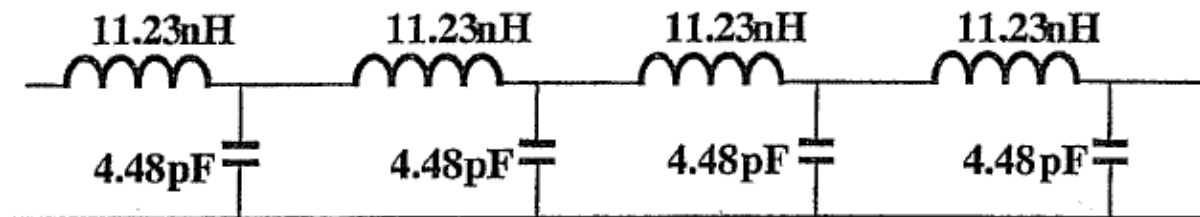
- The capacitance and inductance for a single segment are

$$C_{\text{segment}} = \frac{C_{\text{total}}}{\text{segments}} = \frac{17.9 \text{ pF}}{4} = 4.48 \text{ pF}$$

$$L_{\text{segment}} = \frac{L_{\text{total}}}{\text{segments}} = \frac{44.9 \text{ nH}}{4} = 11.23 \text{ nH}$$

- For checking

$$TD_{\text{segment}} = \sqrt{L_{\text{segment}} C_{\text{segment}}} = \sqrt{(11.23 \text{ nH})(4.48 \text{ pF})} = 0.224 \text{ ns} \leq \frac{T_r}{10}$$



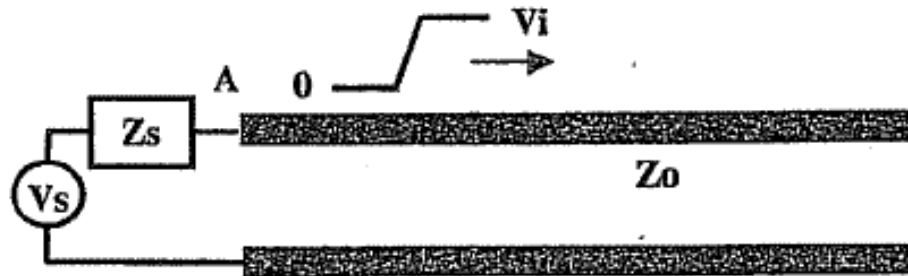
Launching Initial Wave and TX line Reflections

- Initial Wave

- Launching a Wave onto a Long TX Line

- The magnitude of V_i is determined by the voltage divider between the source and the line impedance:

$$V_i = V_s \frac{Z_o}{Z_o + Z_s}$$



- When $Z_L = Z_o$, the voltage V_i is the dc steady-state value.

How long does it take? A time delay: TD

Launching Initial Wave and TX line Reflections

- Initial Wave

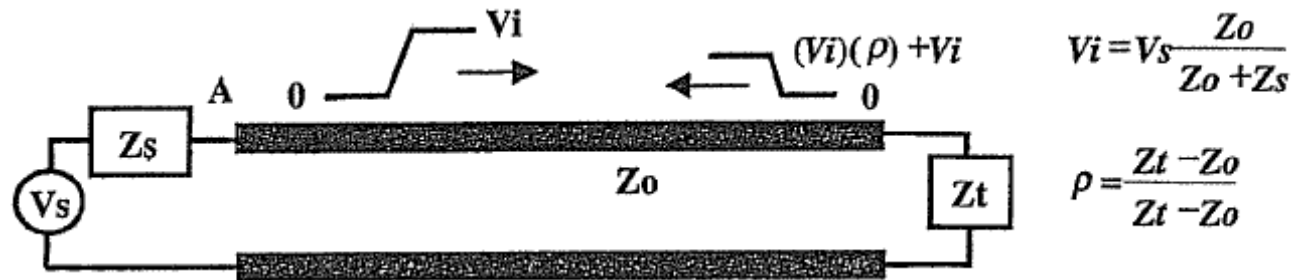
- Incident Signal Being Reflected from an Unmatched Load

- **Junction**: impedance discontinuity on a TX line

- The reflection coefficient is calculated as:

$$\rho = \frac{V_{\text{reflected}}}{V_{\text{incident}}} = \frac{Z_t - Z_o}{Z_t + Z_o}$$

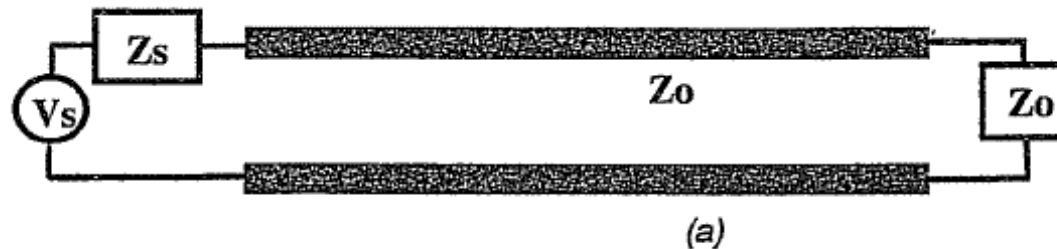
- This reflection and counter-reflection continues until the line has reached a stable condition.



Launching Initial Wave and TX line Reflections

- Initial Wave

- Matched, Shorted and Open Loads



$$\rho = \frac{Z_o - Z_o}{Z_o + Z_o} = 0$$



$$\rho = \frac{0 - Z_o}{0 + Z_o} = -1$$

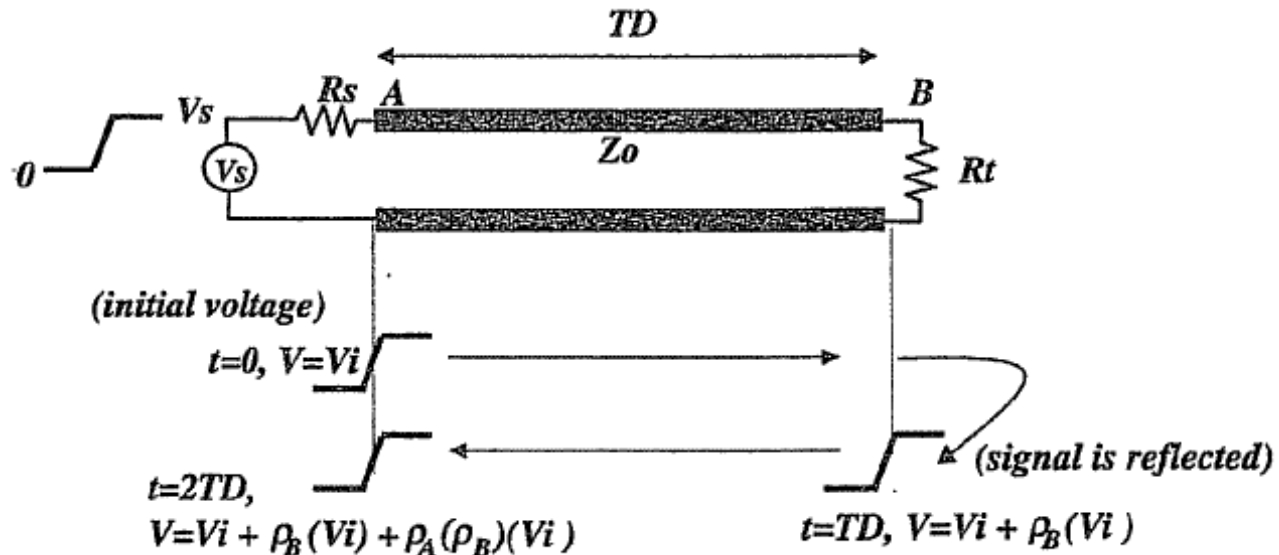


$$\rho = \frac{\infty - Z_o}{\infty + Z_o} = 1$$

Launching Initial Wave and TX line Reflections

- Multiple Reflections
 - Descriptions

$$V_i = V_s Z_o / (Z_o + R_s)$$



- The reflections could **take a long time** to settle out if the termination is **not matched** and can have some significant **timing impacts**.

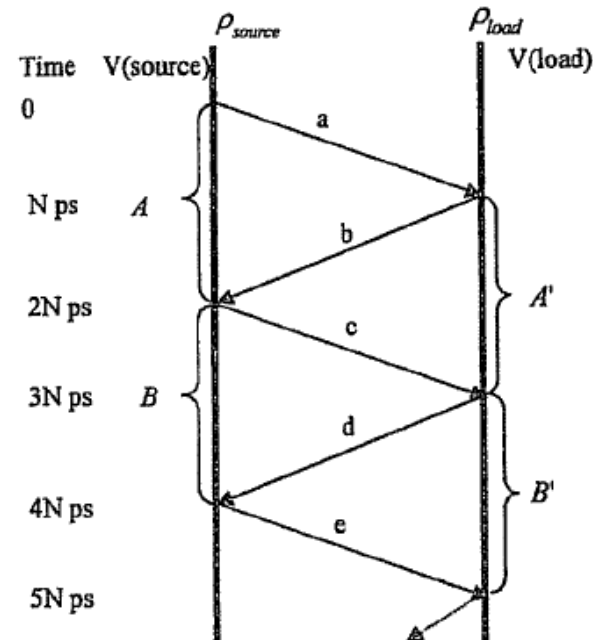
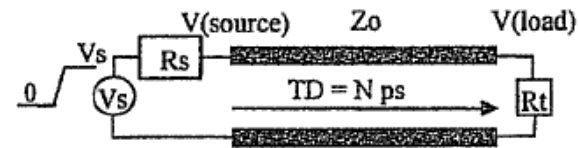
Launching Initial Wave and TX line Reflections

- Multiple Reflections

- Lattice Diagrams

- A bounce diagram
- Diagonal lines: waves
- Increasing time: ↓
- Time increment: TD
- The steady state V :

$$V_s \frac{R_t}{R_t + R_s}$$



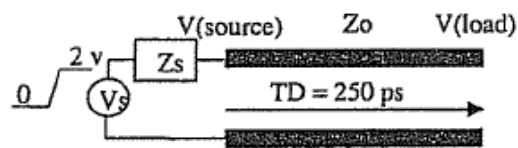
$$\begin{aligned} a &= V_{\text{initial}} \\ b &= a \rho_{\text{load}} \\ c &= b \rho_{\text{source}} \\ d &= c \rho_{\text{load}} \\ e &= d \rho_{\text{source}} \\ f &= e \rho_{\text{load}} \end{aligned}$$

$$\begin{aligned} A &= a \\ B &= a + b + c \\ C &= a + b + c + d + e \\ A' &= a + b \\ B' &= a + b + c + d \\ C' &= a + b + c + d + e + f \end{aligned}$$

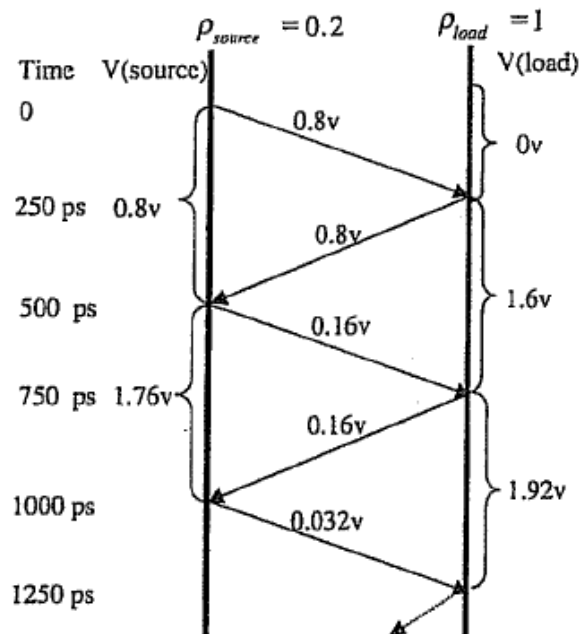
Launching Initial Wave and TX line Reflections

• Lattice Diagrams and Over- and Underdriven TX Lines

– Example 2.2 Underdriven TX Line ($Z_0 < Z_s$)



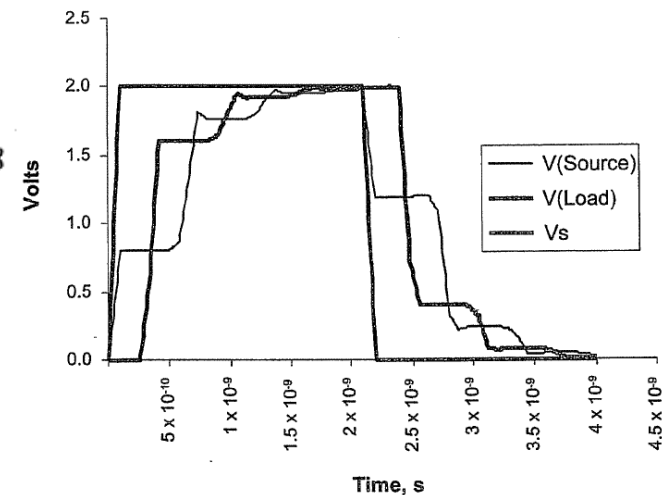
Assume $Z_s = 75$ ohms
 $Z_0 = 50$ ohms
 $V_s = 0-2$ volts



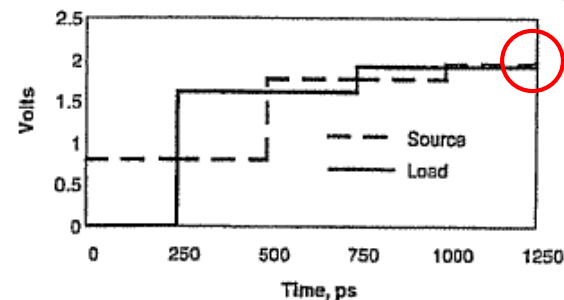
$$V_{initial} = V_s \frac{Z_0}{Z_s + Z_0} = (2) \left(\frac{50}{75 + 50} \right) = 0.8$$

$$\rho_{source} = \frac{Z_s - Z_0}{Z_s + Z_0} = \frac{75 - 50}{75 + 50} = 0.2$$

$$\rho_{load} = \frac{Z_L - Z_0}{Z_L + Z_0} = \frac{\infty - 50}{\infty + 50} = 1$$



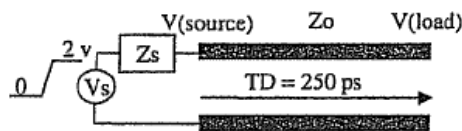
Response from lattice diagram



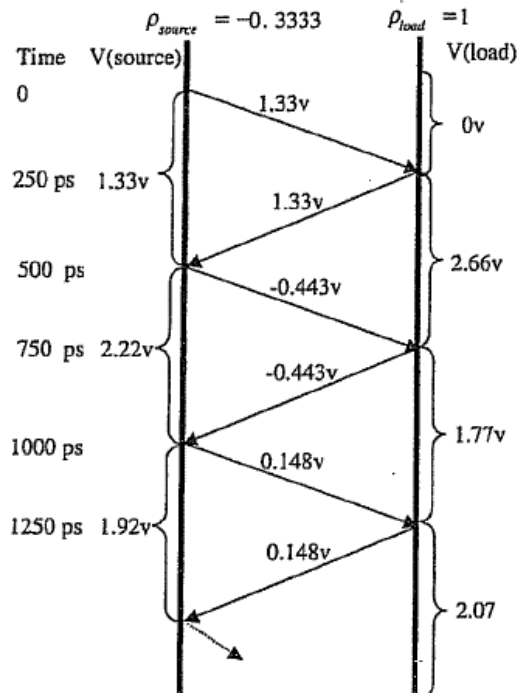
Launching Initial Wave and TX line Reflections

• Lattice Diagrams and Over- and Underdriven TX Lines

– Example 2.2 Overdriven TX Line ($Z_0 > Z_s$)



Assume $Z_s = 25$ ohms
 $Z_o = 50$ ohms
 $V_s = 0-2$ volts

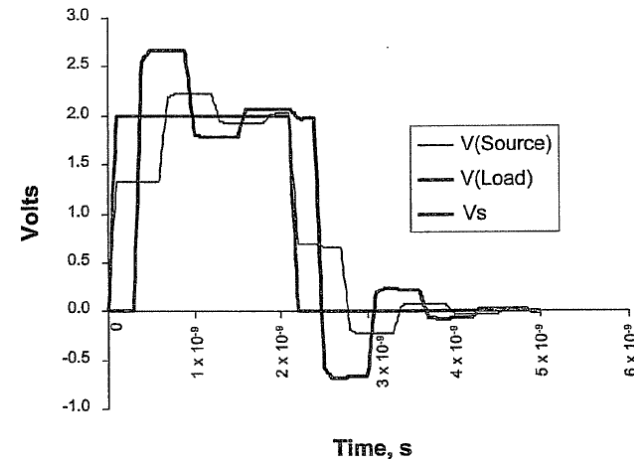
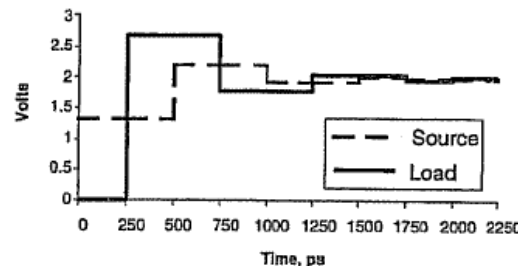


$$V_{initial} = V_s \frac{Z_o}{Z_s + Z_o} = (2) \left(\frac{50}{25 + 50} \right) = 1.3333$$

$$\rho_{source} = \frac{Z_s - Z_o}{Z_s + Z_o} = \frac{25 - 50}{25 + 50} = -0.33333$$

$$\rho_{load} = \frac{Z_L - Z_o}{Z_L + Z_o} = \frac{\infty - 50}{\infty + 50} = 1$$

Response from lattice diagram

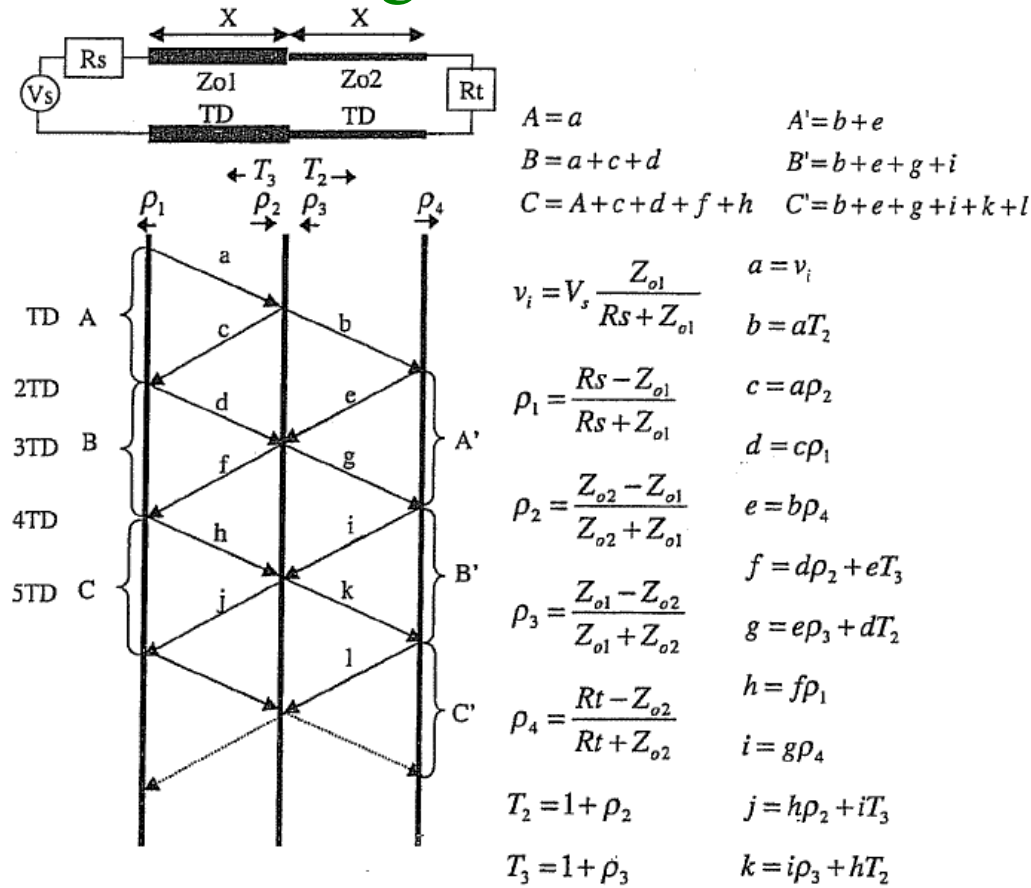


Ringing effect

Launching Initial Wave and TX line Reflections

- Lattice Diagrams and Over- and Underdriven TX Lines

- Two Segments of TX Lines



At the junction of Z_{o1}/Z_{o2} , part of the signal will be reflected (ρ) and part of the signal will be transmitted ($T=1+\rho$)

How about the signal at the junction Z_{o1}/Z_{o2} ?

Launching Initial Wave and TX line Reflections

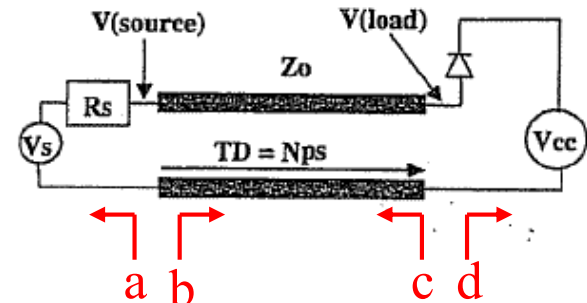
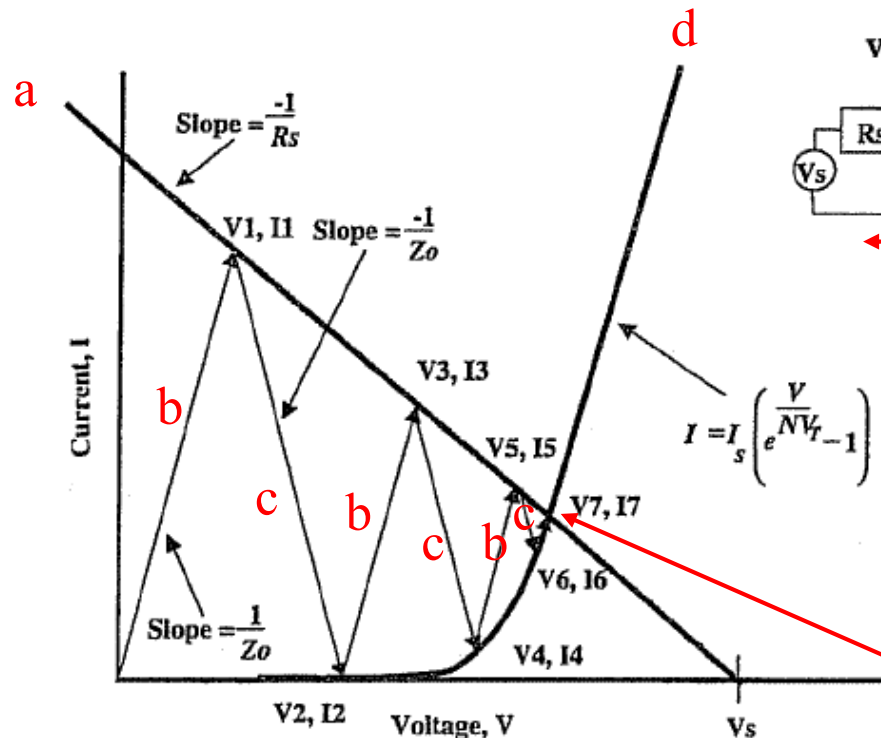
• Bergeron Diagrams and Reflections from Nonlinear Loads

– Bergeron Diagrams

Solve for the intersections of the source (a, b)
Solve for the intersections of the load (c, d)

- When **nonlinear loads and sources** exist.

$V_1 = ?$



Response from Bergeron Diagram

Time	$V(\text{source})$	$V(\text{load})$
0	V_1	0
N	V_1	V_2
2N	V_3	V_2
3N	V_3	V_4
4N	V_5	V_4
5N	V_5	V_6
6N	V_7	V_6
7N	V_7	V_7
8N	V_7	V_7

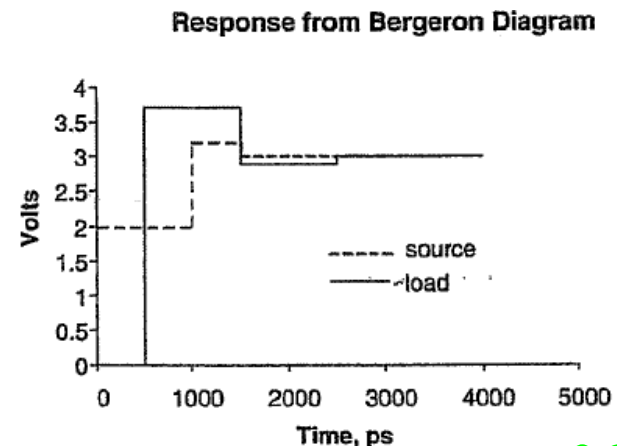
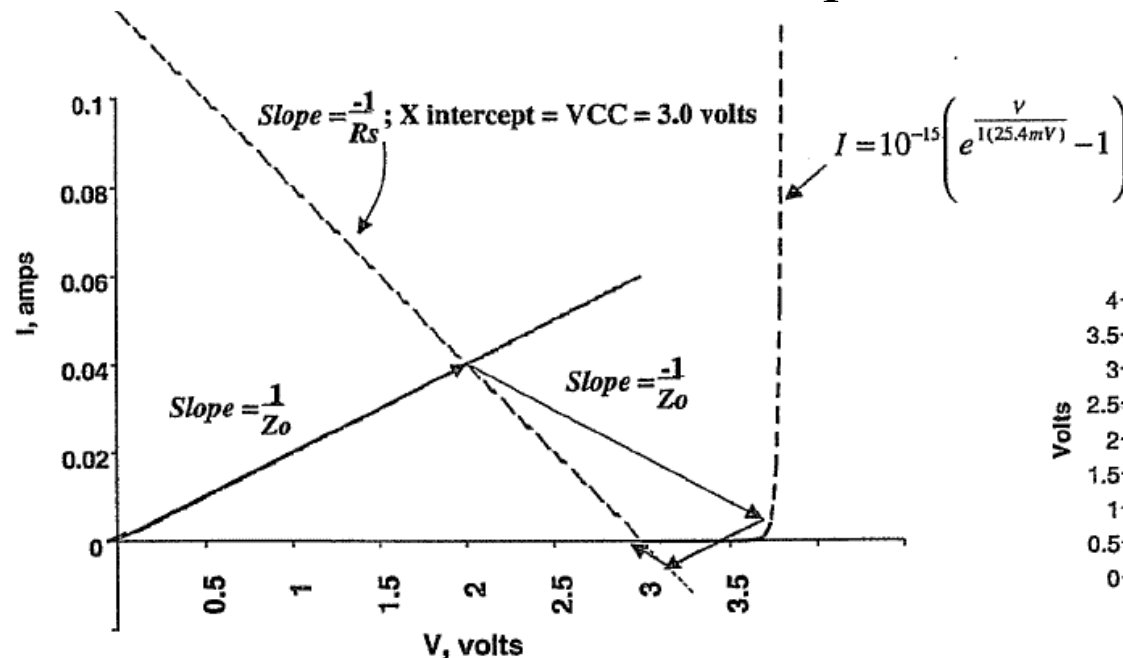
Steady state point

Launching Initial Wave and TX line Reflections

- Bergeron Diagrams and Reflections from Nonlinear Loads

- Example of Bergeron Diagrams

- $V_S=3V$, $TD = 500ps$, $Z_0=50\Omega$, $R_S=25\Omega$, and the diode behaves with the equation shown.

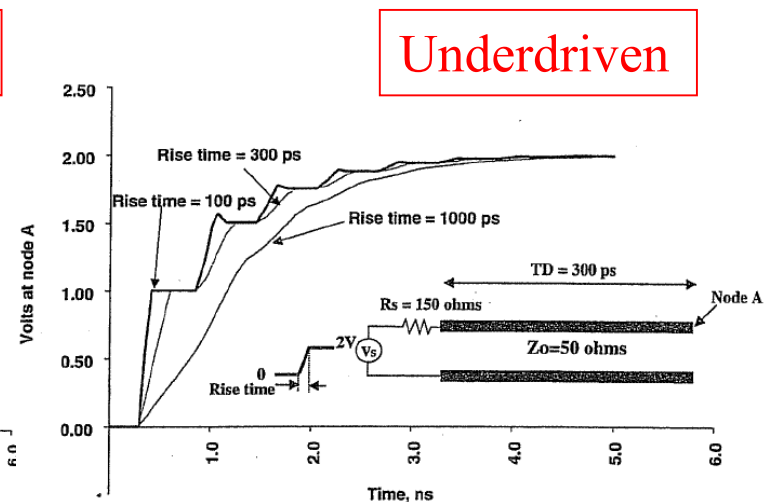
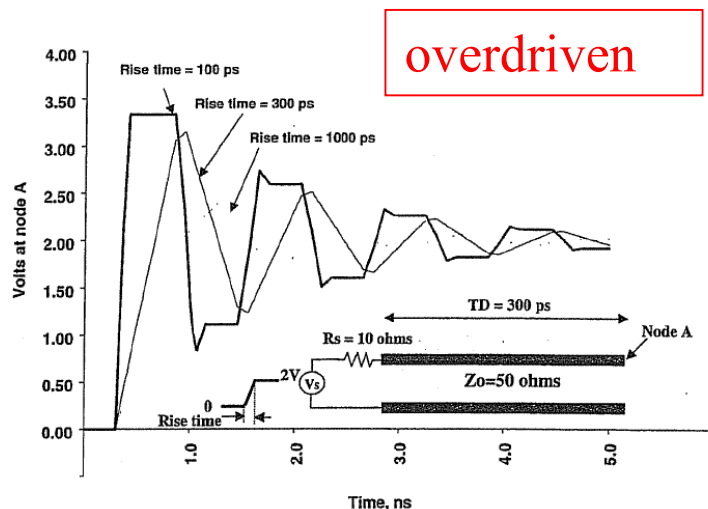


Launching Initial Wave and TX line Reflections

- Effect of Rise Time on Reflections

- Criterion

- The rise time will begin to **have a significant effect** on the waveform when : $\tau_r < 2TD$.
- When $\tau_r > 2TD$** , reflection from the source will occur **at a time in the transition region**, which will not affect the steady state value.



Launching Initial Wave and TX line Reflections

- Reflections from Reactive Loads
 - Reflections from Capacitive Loads-No Loss
 - The capacitor will initially look like a short circuit when the signal reaches the capacitor and will look like an open circuit after the capacitor is fully charged.

What is the effect of t_r on the waveform?

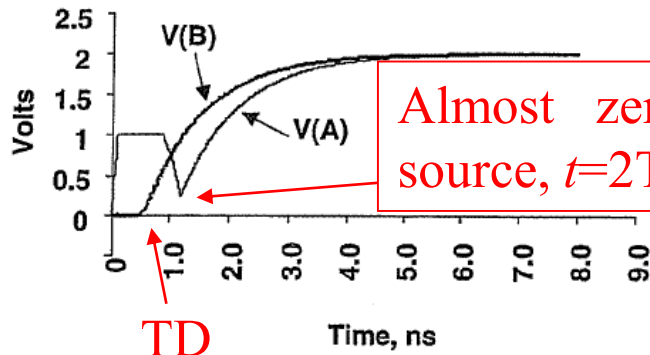
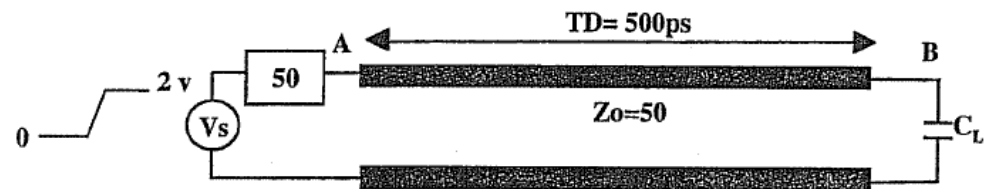
The signal data rate is slow down by adding C_L .

The voltage at the capacitor is

$$V_{\text{capacitor}} = 2V_i(1 - e^{-(t-TD)/\tau}), \quad t > TD$$

$$\tau = CZ_o$$

$$v(t) = V_{oc} + (v(0) - V_{oc})e^{-t/(R_i C)}$$



Almost zero at the source, $t=2TD$

Launching Initial Wave and TX line Reflections

- Reflections from Reactive Loads
 - Reflections from Capacitive Loads-Lossy
 - If the line is terminated with a parallel resistor and capacitor, the voltage at the capacitor will be

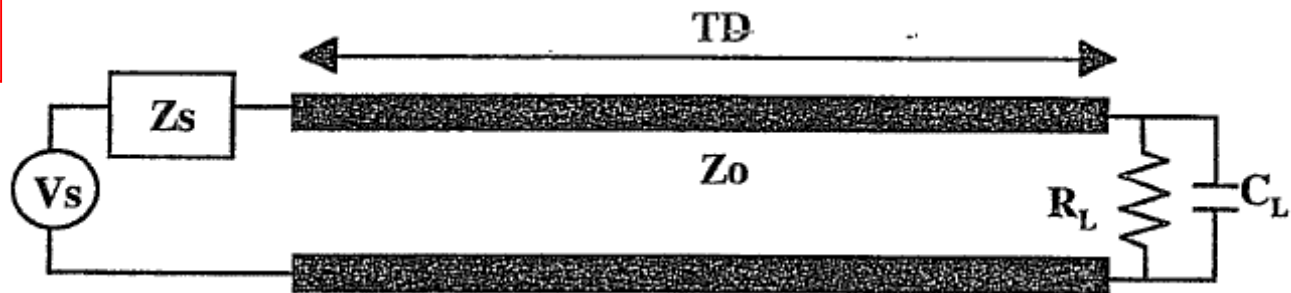
$$V_{\text{capacitor}} = 2V_i \frac{R_L}{R_L + Z_0} (1 - e^{-(t-TD)/\tau_1}), \quad t > TD$$

With $Z_S = Z_0$

$$\tau_1 = \frac{C_L Z_0 R_L}{R_L + Z_0}$$

By adding R_L , τ_1 could be made smaller.

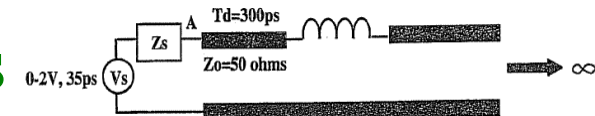
The time constant depends on C_L and the parallel combination of R_L and Z_0 .



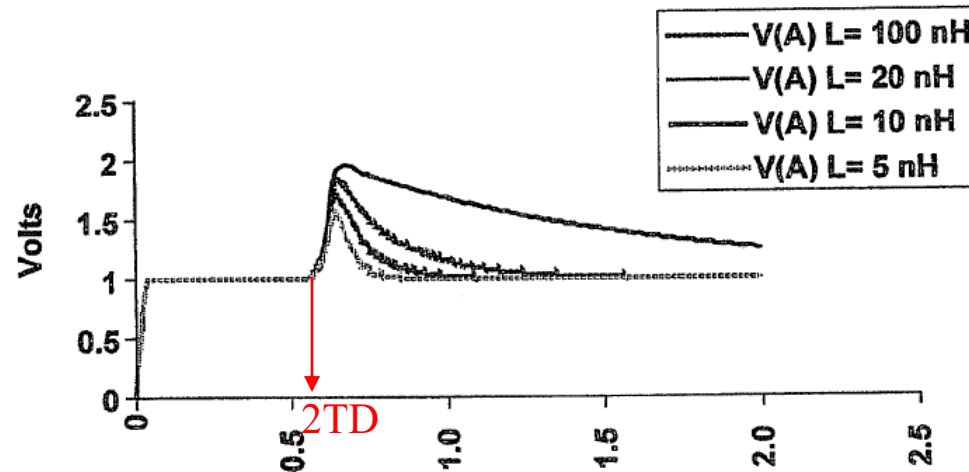
Launching Initial Wave and TX line Reflections

- Reflections from Reactive Loads

- Reflections from Inductive Loads



- Initially, at time = 0, the inductor will resemble an open circuit. This produces a reflection coefficient of 1.
- Eventually, the inductor will discharge its energy at a rate that depends on the time constant τ of L/Z_0 .



What if the series L was replaced with an parallel C ?

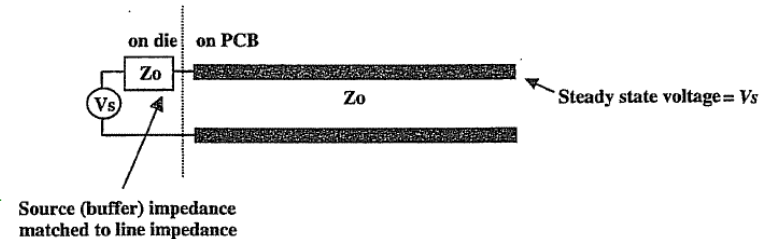
Launching Initial Wave and TX line Reflections

- Termination Schemes to Eliminate Reflections
 - Two Impractical and One Practical Methods
 - Method 1: to decrease the frequency of the system so that the reflections on the TX line reach steady state before another signal is driven onto the line
 - Method 2: to shorten the PCB traces so that the reflections will reach steady state in a shorter time.
 - **Method 3:** to terminate the TX line with an impedance equal to the characteristic impedance of the line.
 - Source termination
 - Load (Parallel) termination

Launching Initial Wave and TX line Reflections

- Termination Schemes to Eliminate Reflections

- On-Die Source Termination



- This method requires that the I - V curve of the output buffer be very linear and yield an I - V curve with an impedance very close to the TX line impedance.
- Advantages*: this does not require any additional components that increase cost and consume area on the board.
- Disadvantages*: since there are numerous variables, it is difficult to achieve a good match. Some of them are silicon fabrication process variations, voltage, temperature, power delivery factors, and simultaneous switching noise.

Launching Initial Wave and TX line Reflections

• Termination Schemes to Eliminate Reflections

– Series Source Termination

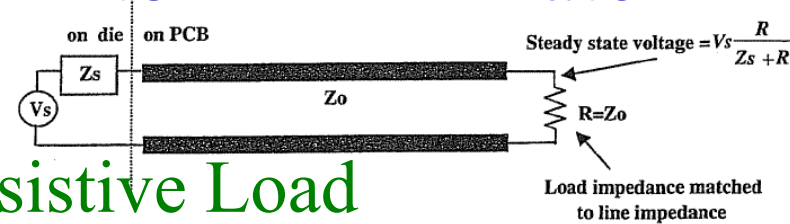


- This method requires that a resistor be added in series with the output buffer to match the characteristic impedance of the TX line.
- Designing the I - V curve of the output buffer to yield a very low impedance so that the matching mechanism is dominated by the series resistor.
- *Advantage*: the total variation in impedance is small.
- *Disadvantage*: the resistors add cost to the board, and it consumes significant board area.

Launching Initial Wave and TX line Reflections

• Termination Schemes to Eliminate Reflections

– Load Termination with Resistive Load

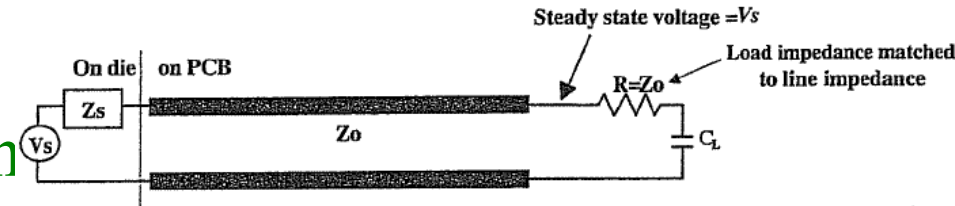


- Load termination with a resistive load **eliminates the unknown variables** associated with the buffer impedance because **a precision resistor** can be used.
- *Advantage*: **low-impedance output buffers** may be used.
- *Disadvantage*: a large portion of the **dc current** will be shunted to ground, which **exacerbates power delivery and thermal problems**. As power consumption increases, cost also increases.

Launching Initial Wave and TX line Reflections

• Termination Schemes to Eliminate Reflections

– AC Load Termination



- AC load termination uses a series capacitor and resistor at the load end. $R=Z_0$, $RC_L=1\sim 2\tau_r$.
- *Advantage*: the power is only dissipated during the transition region. Thus, no dc power dissipation.
- *Disadvantage*: the capacitive loading will increase the signal delay by slowing down the rising or falling times at the load. Furthermore, additional resistors and capacitors consume board area and increase cost.

Launching Initial Wave and TX line Reflections

- Termination Schemes to Eliminate Reflections

- Common Termination Problems

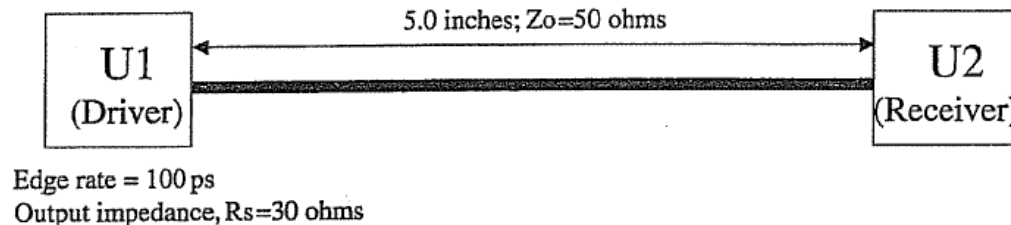
- *Fabrication Variation*: the characteristic impedance of the trace tends to vary significantly, due to PCB production variations. This tends to have a bigger impact on source termination.
- *Crosstalk*: will introduce additional variations in the impedance.
- Different line lengths:
 - For short lines, source termination is desirable. Since DC levels are prolonged, we don't want to consume them.
 - For long lines, load termination is preferable. Since we don't want the wave to be reflected toward the source.

Additional Examples

- Design of a Trace

- Problem

- The driving buffers on component U1 have an impedance of $30\ \Omega$, an edge rate of 100 ps, and a swing of 0 to 2 V.
 - The traces on the PCB are required to be $50\ \Omega$ and 5 in. long.
 - The relative dielectric constant of the board (ϵ_r) is 4.0, the transmission line is assumed to be a perfect conductor, and the receiver capacitance is small enough to be ignored.

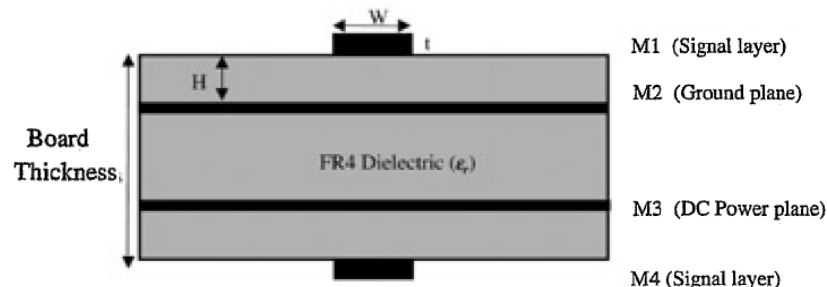


Additional Examples

- Design of a Trace

- Goals

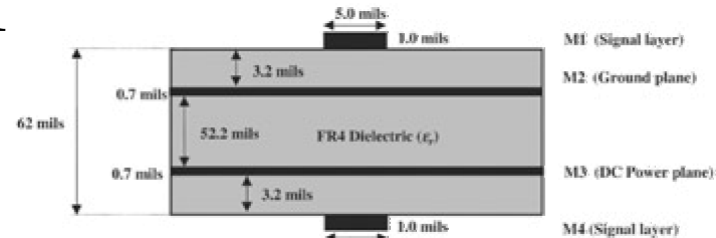
- 1. Determine the **correct cross-sectional geometry** of the PCB trace **in microstrip form** that will yield an impedance of $50\ \Omega$.
 - 2. Calculate **the time** it takes for the signal to travel **from the driver, U1, to the receiver, U2**.
 - 3. Determine the **wave shape seen at U2** when the system is driven by U1.
 - 4. Create **an equivalent circuit** of the system.



Additional Examples

- Design of a Trace

- Calculating the Cross-Sectional Geometry of the PCB



- For the purpose of transmission line design, a dc power plane will act like an ac ground.
 - The trace impedance in microstrip form is

$$Z_{o_{\text{microstrip}}} = \frac{87}{\sqrt{\epsilon_r + 1.41}} \ln \frac{5.98H}{0.8W + t}$$

- Since the standard $t=1.0\text{mil}$ and $W=5\text{mil}$, thus we have

$$50 = \frac{87}{\sqrt{4.0 + 1.41}} \ln \frac{5.98H}{0.8(5.0) + 1.0} \longrightarrow H = 3.2 \text{ mils}$$

- Since the internal metal layers are only 0.7 mil thick and a typical PCB board thickness requested by industry is 62 mils thick, 52.2 mil is determined.

Additional Examples

- Design of a Trace

- Calculating the Propagation Delay

- The effective dielectric constant is

$$\epsilon_e = \frac{\epsilon_r + 1}{2} + \frac{\epsilon_r - 1}{2} \left(1 + \frac{12H}{W} \right)^{-1/2} + F - 0.217(\epsilon_r - 1) \frac{t}{\sqrt{WH}}$$

- Since $W/H = 5/3.2 > 1.0$, then $F = 0$. Therefore,

$$\begin{aligned} \epsilon_e &= \frac{4.0 + 1}{2} + \frac{4.0 - 1}{2} \left[1 + \frac{12(3.2)}{5.0} \right]^{-1/2} + 0 - 0.217(4.0 - 1) \frac{1.0}{\sqrt{5.0(3.2)}} \\ &= 2.84 \end{aligned}$$

- The propagation velocity is

$$v = \frac{c}{\sqrt{\epsilon_r}} = \frac{3.0 \times 10^8 \text{ m/s}}{\sqrt{2.84}} = 1.78 \times 10^8 \text{ m/s}$$

- The time delay is

$$\text{TD} = \frac{\text{length} \sqrt{\epsilon_r}}{c} = \frac{5.0 \text{ in.}}{1.78 \text{ m/s}} \left(\frac{0.0254 \text{ m}}{1.0 \text{ in.}} \right) = 713 \text{ ps}$$

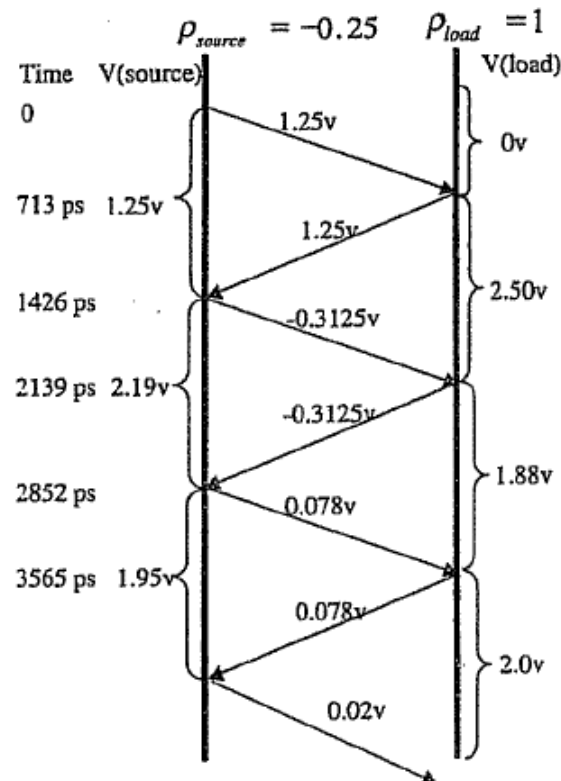
Additional Examples

- Design of a Trace

- Determining the Wave Shape Seen at the Receiver

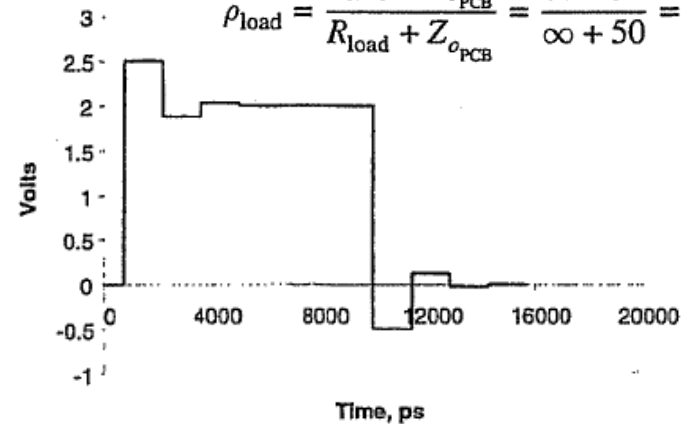
$$V_{\text{initial}} = V_{\text{in}} \frac{Z_{o_{\text{PCB}}}}{Z_{o_{\text{PCB}}} + R_s} = 2.0 \left(\frac{50}{50 + 30} \right) = 1.25 \text{ V}$$

- Assuming $R_{\text{Load}} = \infty$ and using the lattice diagram,



$$\rho_{\text{source}} = \frac{R_s - Z_{o_{\text{PCB}}}}{R_s + Z_{o_{\text{PCB}}}} = \frac{30 - 50}{30 + 50} = -0.25$$

$$\rho_{\text{load}} = \frac{R_{\text{load}} - Z_{o_{\text{PCB}}}}{R_{\text{load}} + Z_{o_{\text{PCB}}}} = \frac{\infty - 50}{\infty + 50} = 1.0$$



Additional Examples

- Design of a Trace

- Creating an Equivalent Circuit

- The minimum of 72 segments is required.

$$\text{velocity (in./ps)} = \frac{5.0 \text{ in.}}{713 \text{ ps}} = 0.0070 \text{ in./ps}$$

$$\text{segments} \geq 10 \left(\frac{\text{length}}{T_r v} \right) = 10 \left[\frac{5 \text{ in.}}{(100 \text{ ps})(0.0070 \text{ in./ps})} \right] = 71.4$$

- Since $Z_o = \sqrt{L/C}$ and $\text{TD} = \sqrt{LC}$, we have

$$C = \frac{\text{TD}}{Z_o} = \frac{\sqrt{LC}}{\sqrt{L/C}} = \frac{142.6 \text{ ps}}{50} = 2.85 \text{ pF}$$

TD per inch

$$L = (\text{TD})(Z_o) = \sqrt{LC} \sqrt{\frac{L}{C}} = 7.130 \text{ nH}$$

- The inductance and capacitance per segment are

$$C_{\text{segment}} = \frac{(\text{length})(C/\text{in.})}{\text{segment}} = \frac{5.0 \text{ in.}(2.85 \text{ pF/in.})}{72} = 0.198 \text{ pF/segment}$$

$$L_{\text{segment}} = \frac{(\text{length})(L/\text{in.})}{\text{segment}} = \frac{5.0 \text{ in.}(7.13 \text{ nH/in.})}{72} = 0.495 \text{ nH/segment}$$

Additional Examples

- Design of a Trace
 - Creating an Equivalent Circuit
 - Check the calculations with

$$\text{delay/segment} = \frac{713 \text{ ps}}{72} = 9.9 \text{ ps} \approx \sqrt{(0.198 \text{ pF})(0.495 \text{ nH})} = 9.9 \text{ ps}$$

$$\text{impedance/segment} = \sqrt{\frac{0.495 \text{ nH}}{0.198 \text{ pF}}} = 50 \Omega$$

- The equivalent circuit is shown below with the open circuit at the end of the line approximated with a very large resistor.

